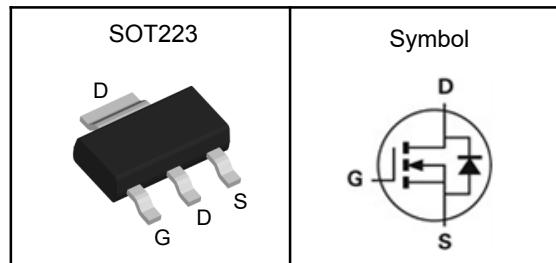


N-Channel Enhancement Mode MOSFET

Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant
- 100% UIS and Rg Tested

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	150	V
$R_{DS(ON)-Typ}$	130	$m\Omega$
I_D	4	A

Absolute Maximum Ratings ($T_A=25^\circ C$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	150	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
$I_{DM}^{①}$	Pulse Drain Current Tested	16	A
I_D	Continuous Drain Current	4	A
P_D	Maximum Power Dissipation	4	W

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{②}$	Thermal Resistance-Junction to Ambient	31	$^\circ C/W$

Note ① : Max. current is limited by bonding wire.

Note ② : Surface Mounted on 1in² FR-4 board with 1oz.

N-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	150	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=150\text{V}, \text{V}_{\text{GS}}=0\text{V}$	---	---	1	μA
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	1.5	2.0	2.5	V
I_{GSS}	Gate Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$\text{R}_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=4\text{A}$	---	130	175	$\text{m}\Omega$
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=25\text{V}, \text{Freq.}=1\text{MHz}$	---	900	---	pF
C_{oss}	Output Capacitance		---	115	---	
C_{rss}	Reverse Transfer Capacitance		---	70	---	
$\text{T}_{\text{d(on)}}$	Turn-on Delay Time	$\text{V}_{\text{GS}}=10\text{V}, \text{V}_{\text{DD}}=75\text{V}, \text{R}_G=6\Omega$	---	8	---	nS
T_r	Turn-on Rise Time		---	10	---	
$\text{T}_{\text{d(off)}}$	Turn-off Delay Time		---	20	---	
T_f	Turn-off Fall Time		---	15	---	
Q_g	Total Gate Charge	$\text{V}_{\text{GS}}=10\text{V}, \text{V}_{\text{DD}}=75\text{V}, \text{I}_D=4\text{A}$	---	19	---	nC
Q_{gs}	Gate-Source Charge		---	5.5	---	
Q_{gd}	Gate-Drain Charge		---	7	---	
Source-Drain Characteristics						
V_{SD}	Diode Forward Voltage	$\text{I}_S=4\text{A}, \text{V}_{\text{GS}}=0\text{V}$	---	---	1.2	V

N-Channel Enhancement Mode MOSFET

Typical Characteristics

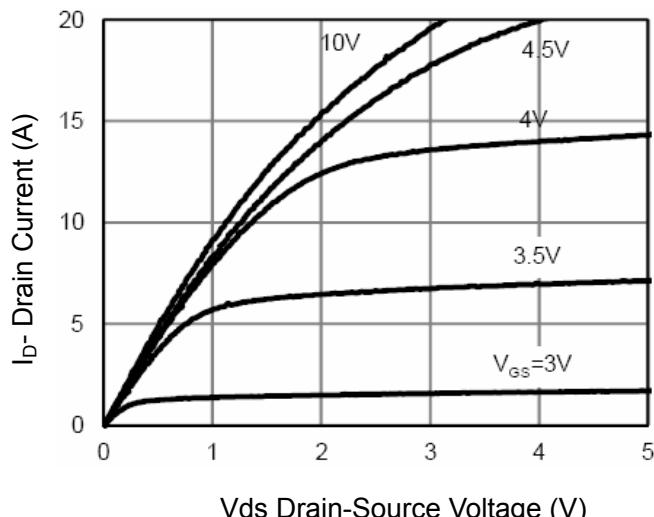


Figure 1 Output Characteristics

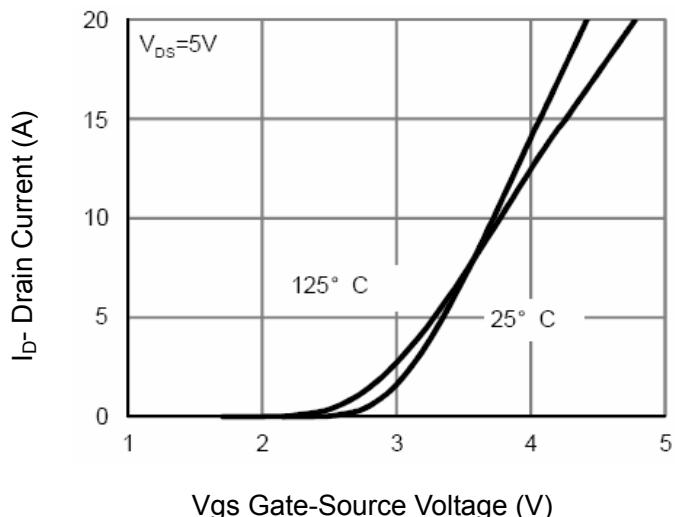


Figure 2 Transfer Characteristics

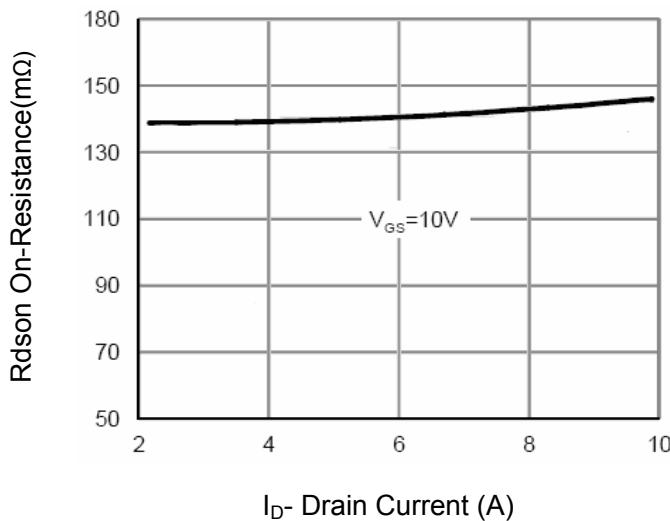


Figure 3 Rdson- Drain Current

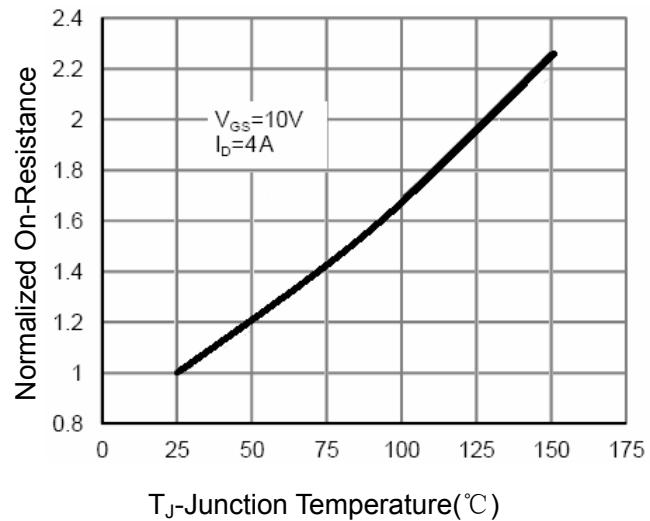


Figure 4 Rdson- Junction Temperature

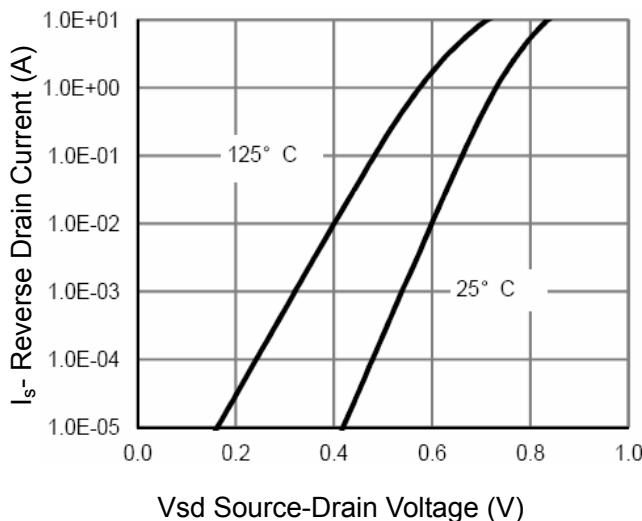


Figure 5 Source- Drain Diode Forward

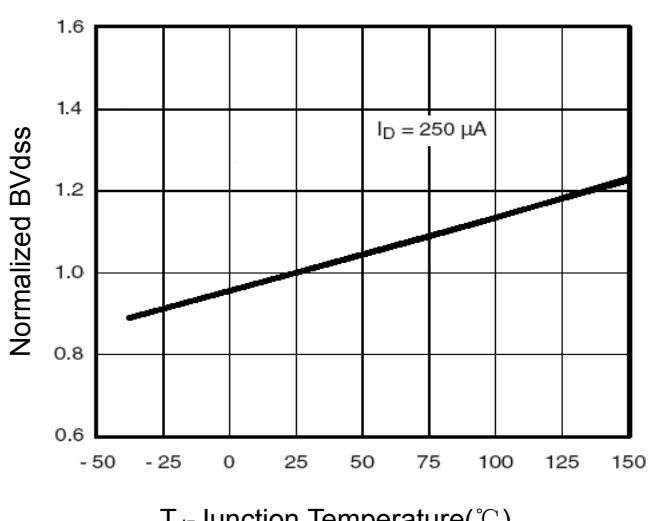


Figure 6 BV_{DSS} vs Junction Temperature

N-Channel Enhancement Mode MOSFET

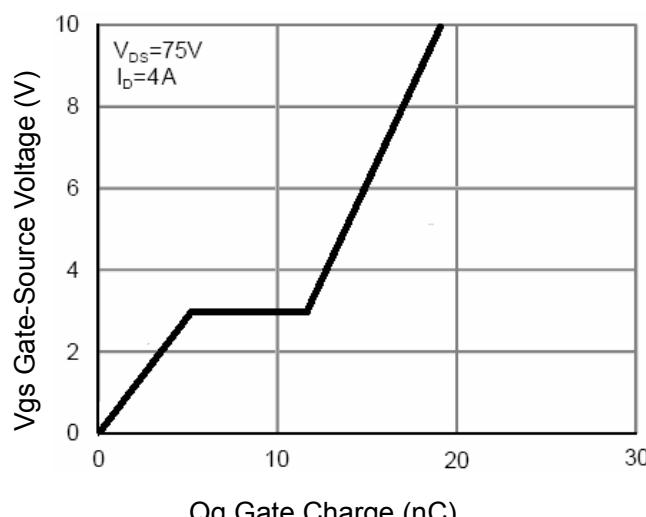


Figure 7 Gate Charge

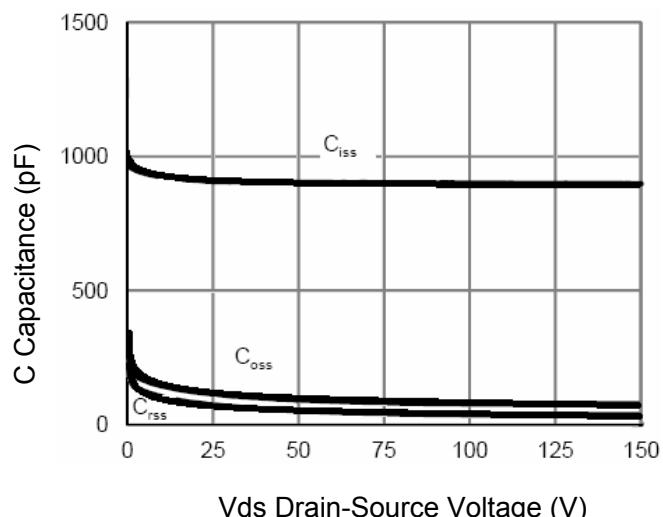


Figure 8 Capacitance vs Vds

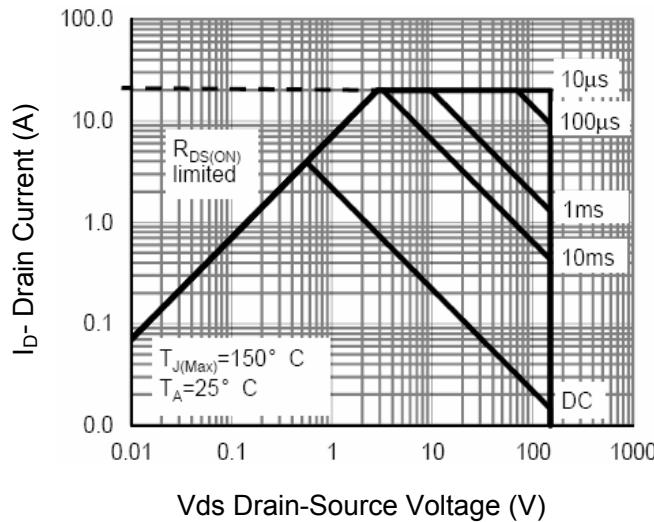


Figure 9 Safe Operation Area

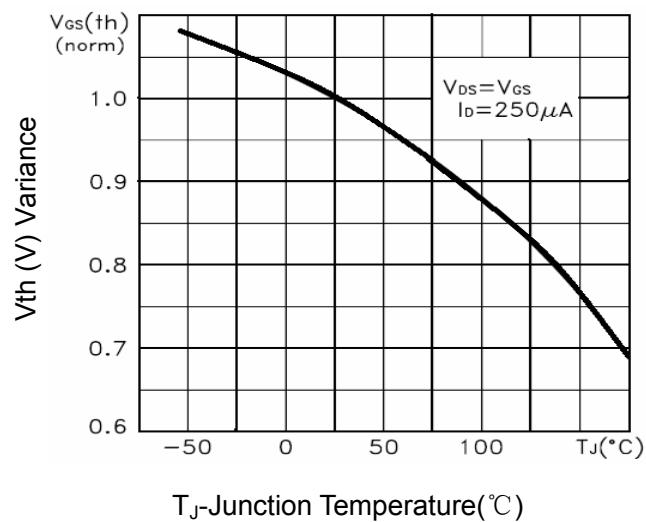


Figure 10 $V_{GS(\text{th})}$ vs Junction Temperature

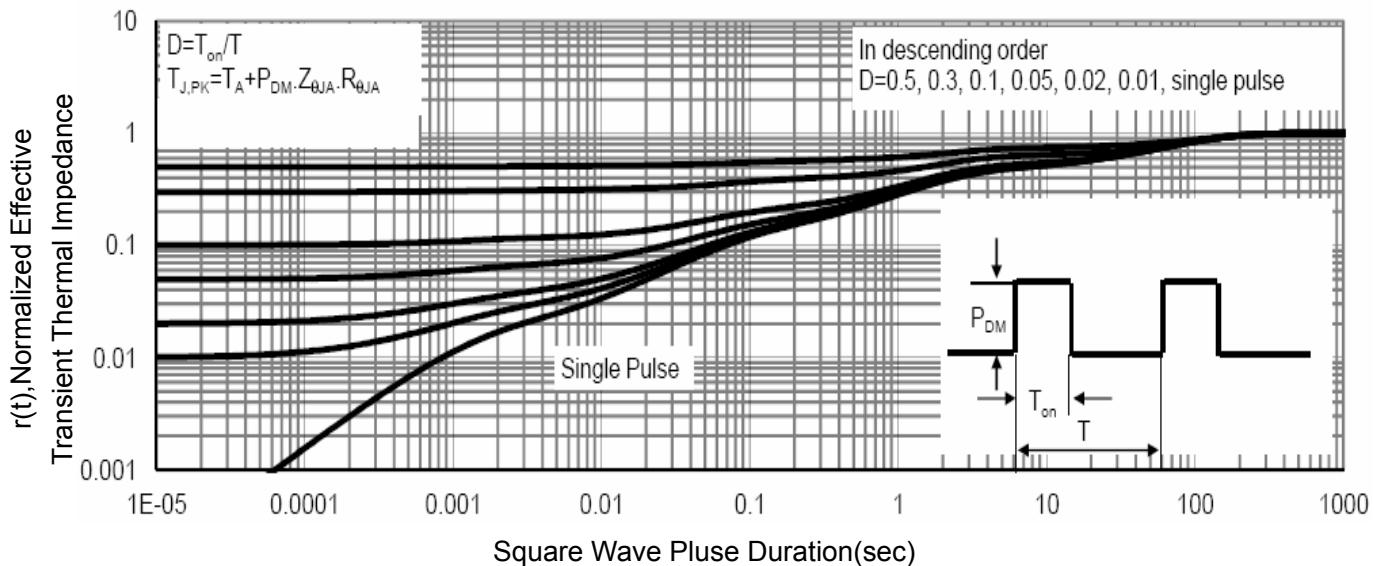
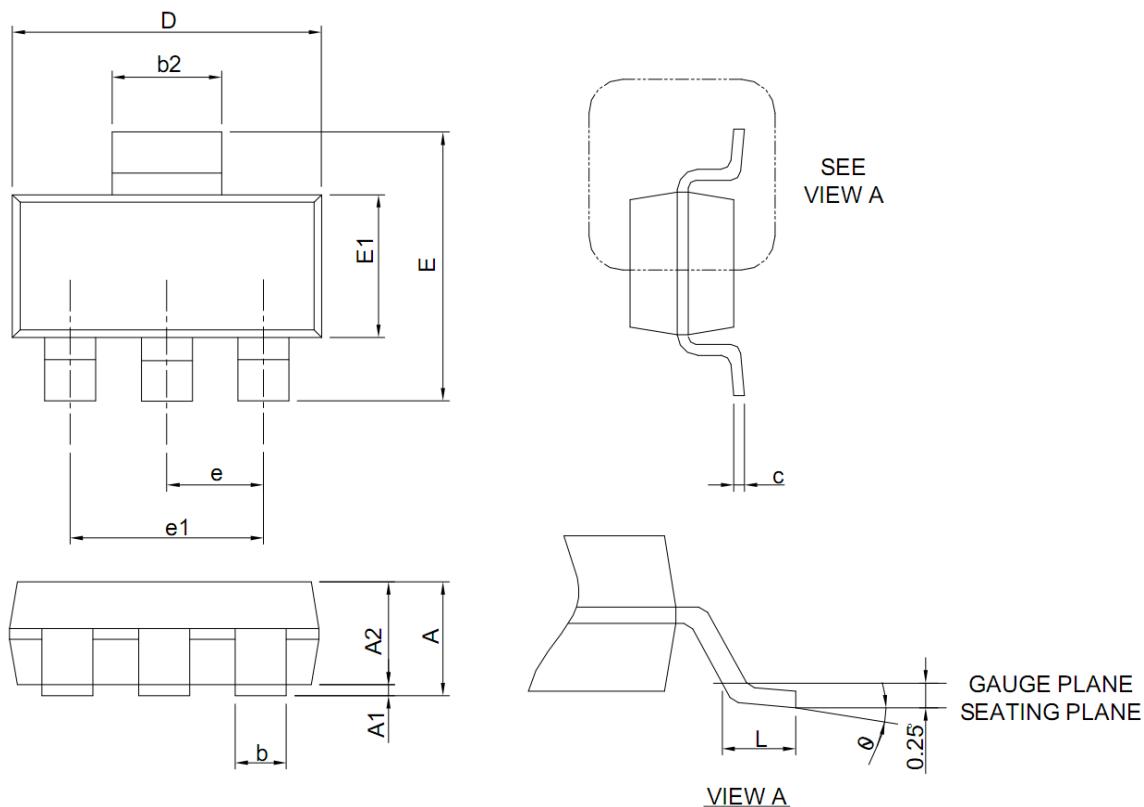


Figure 11 Normalized Maximum Transient Thermal Impedance

N-Channel Enhancement Mode MOSFET
SOT223 Package Outline Data


Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	1.50	1.65	1.80	A1	0.02	0.06	0.10
A2	1.50	1.60	1.70	b	0.66	0.72	0.80
b2	2.90	3.00	3.10	c	0.23	0.30	0.35
D	6.30	6.50	6.70	E	6.70	7.00	7.30
E1	3.30	3.50	3.70	e	2.30 REF		
e1	4.60 REF			L	0.75	--	1.15
θ	0°	--	10°				